



US 20220369458A1

(19) **United States**(12) **Patent Application Publication**  
RYU et al.(10) **Pub. No.: US 2022/0369458 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **PRINTED CIRCUIT BOARD****Publication Classification**(71) Applicant: **LG INNOTEK CO., LTD.**, Seoul (KR)(72) Inventors: **Sung Wuk RYU**, Seoul (KR); **Seung Yul SHIN**, Seoul (KR); **Joon Wook HAN**, Seoul (KR)(21) Appl. No.: **17/771,397**(22) PCT Filed: **Oct. 21, 2020**(86) PCT No.: **PCT/KR2020/014429**

§ 371 (c)(1),

(2) Date: **Apr. 22, 2022**(30) **Foreign Application Priority Data**

Oct. 22, 2019 (KR) ..... 10-2019-0131253

(51) **Int. Cl.****H05K 1/11** (2006.01)**H05K 3/00** (2006.01)**H05K 3/40** (2006.01)(52) **U.S. Cl.**CPC ..... **H05K 1/115** (2013.01); **H05K 1/111** (2013.01); **H05K 3/0032** (2013.01); **H05K 3/4069** (2013.01)

(57)

**ABSTRACT**

A printed circuit board according to an embodiment includes an insulating layer; and a via portion disposed on the insulating layer; wherein the via portion includes: a first pad disposed under the insulating layer; a second pad disposed on the insulating layer; and a via part disposed between the first and second pads in the insulating layer; and wherein a width of the first pad is less than or equal to a width of a lower surface of the via part.

